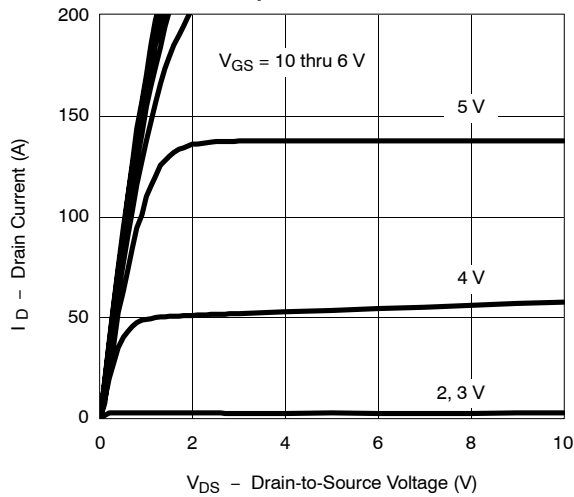
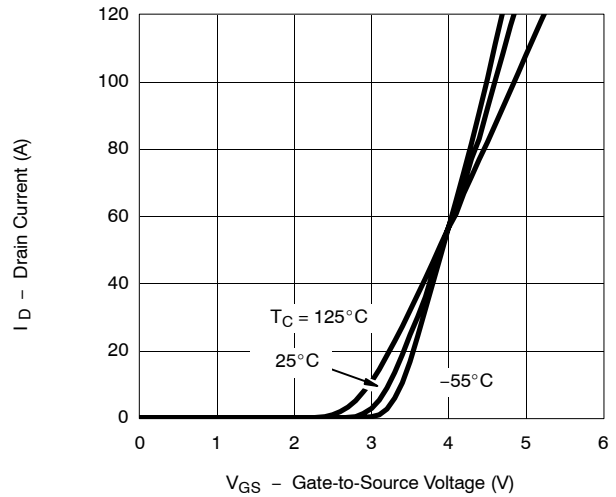
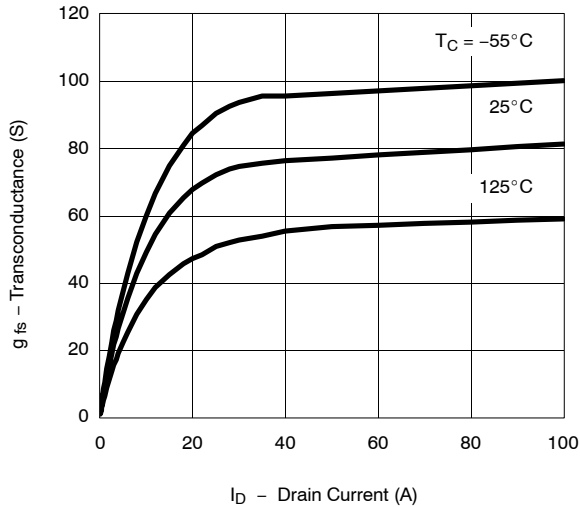
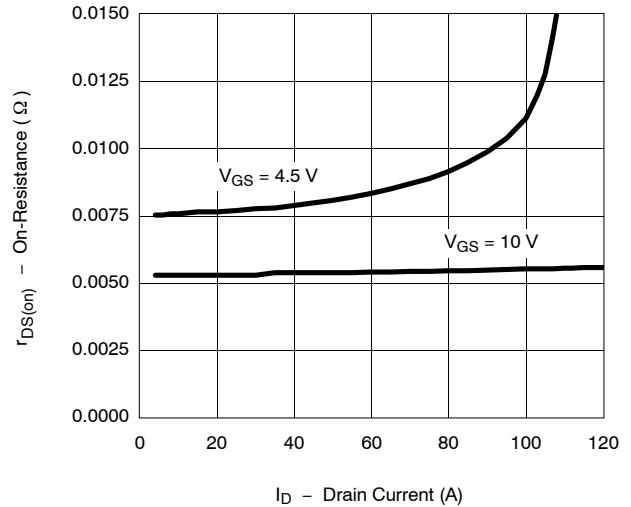
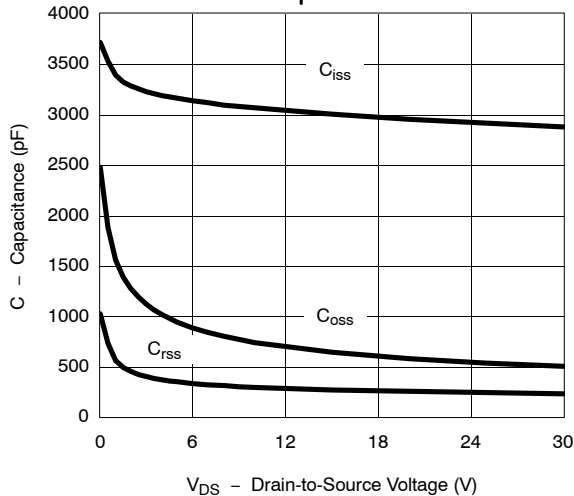
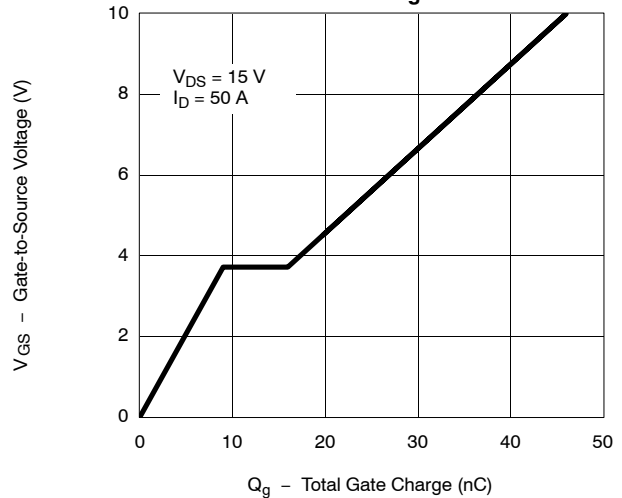


SPECIFICATIONS (T_J = 25 °C UNLESS OTHERWISE NOTED)

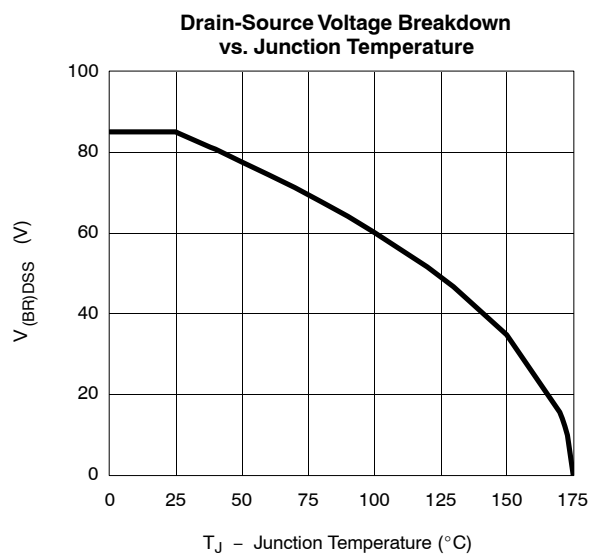
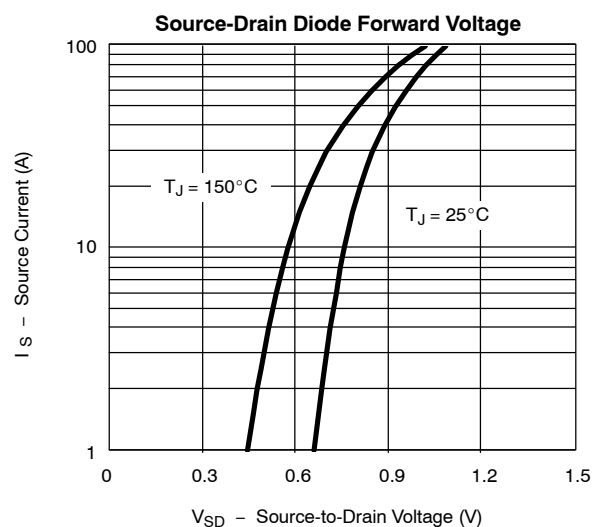
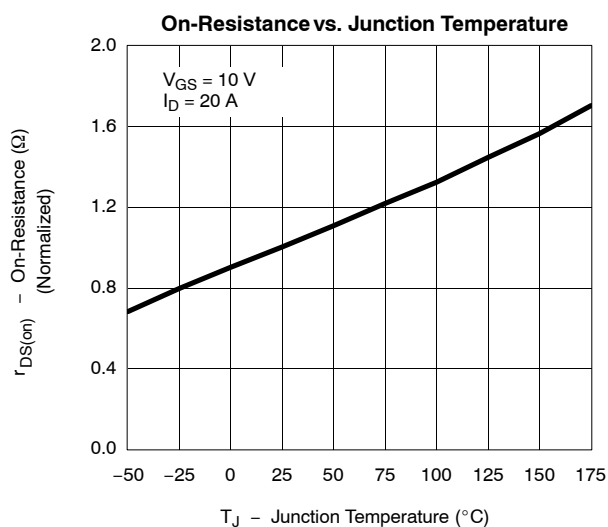
Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Static						
Drain-Source Breakdown Voltage	V _{(BR)DSS}	V _{DS} = 0 V, I _D = 250 μA	30			V
Gate-Threshold Voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = 250 μA	1		3.0	
Gate-Body Leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V			± 100	nA
Zero Gate Voltage Drain Current	I _{DSS}	V _{DS} = 30 V, V _{GS} = 0 V			1	μA
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 125°C			50	
		V _{DS} = 30 V, V _{GS} = 0 V, T _J = 175°C			250	
On-State Drain Current ^a	I _{D(on)}	V _{DS} ≥ 5 V, V _{GS} = 10 V	120			A
Drain-Source On-State Resistance ^a	r _{DS(on)}	V _{GS} = 10 V, I _D = 20 A		0.0054	0.007	Ω
		V _{GS} = 10 V, I _D = 20 A, T _J = 125°C			0.010	
		V _{GS} = 10 V, I _D = 20 A, T _J = 175°C			0.012	
		V _{GS} = 4.5 V, I _D = 20 A		0.0077	0.010	
Forward Transconductance ^a	g _{fs}	V _{DS} = 15 V, I _D = 20 A	20			S
Dynamic ^b						
Input Capacitance	C _{iss}	V _{GS} = 0 V, V _{DS} = 25 V, f = 1 MHz		2900		pF
Output Capacitance	C _{oss}			530		
Reverse Transfer Capacitance	C _{rss}			235		
Gate-Resistance	R _g		1.0	1.9	3.2	Ω
Total Gate Charge ^b	Q _g	V _{DS} = 15 V, V _{GS} = 4.5V, I _D = 50 A		20	30	nC
Gate-Source Charge ^b	Q _{gs}			9		
Gate-Drain Charge ^b	Q _{gd}			7		
Turn-On Delay Time ^b	t _{d(on)}	V _{DD} = 15 V, R _L = 0.3 Ω I _D ≅ 50 A, V _{GEN} = 10 V, R _g = 2.5 Ω		13	20	ns
Rise Time ^b	t _r			9	15	
Turn-Off Delay Time ^b	t _{d(off)}			30	45	
Fall Time ^b	t _f			8	15	
Source-Drain Diode Ratings and Characteristics (T _C = 25°C) ^c						
Continuous Current	I _S				85	A
Pulsed Current	I _{SM}				200	
Forward Voltage ^a	V _{SD}	I _F = 30 A, V _{GS} = 0 V		1.2	1.5	V
Reverse Recovery Time	t _{rr}	I _F = 50 A, di/dt = 100 A/μs		35	70	ns

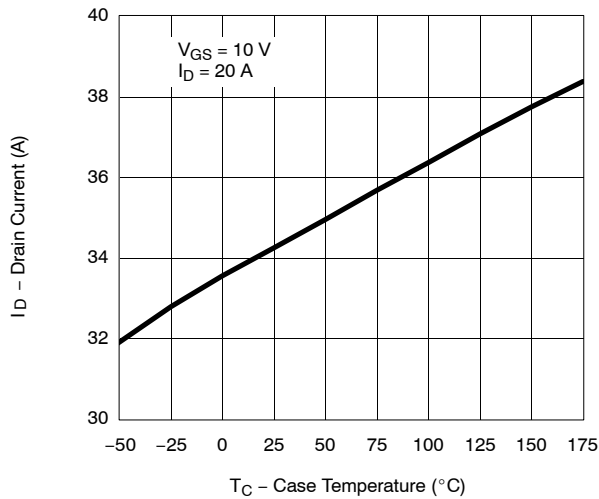
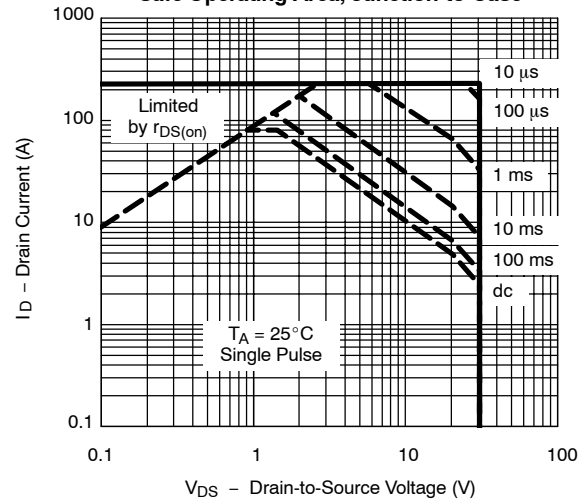
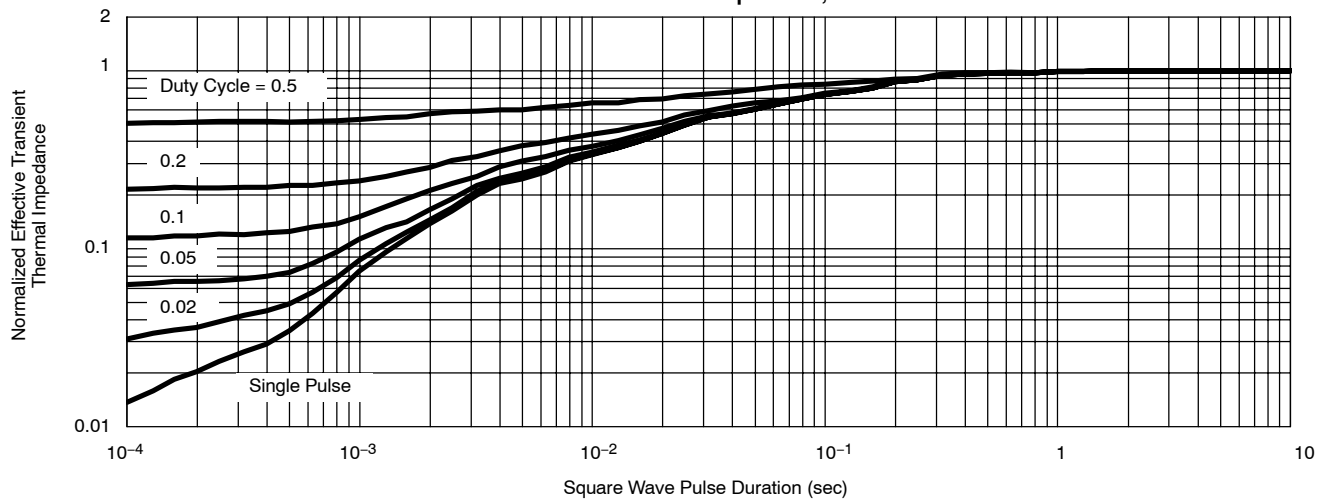
Notes

- a. Pulse test; pulse width ≤ 300 μs, duty cycle ≤ 2%.
b. Independent of operating temperature.
c. Guaranteed by design, not subject to production testing.

**TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)****Output Characteristics****Transfer Characteristics****Transconductance****On-Resistance vs. Drain Current****Capacitance****Gate Charge**

TYPICAL CHARACTERISTICS (25 °C UNLESS NOTED)



**THERMAL RATINGS****Maximum Avalanche Drain Current
vs. Case Temperature****Safe Operating Area, Junction-to-Case****Normalized Thermal Transient Impedance, Junction-to-Case**



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